ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pan	C. Bannockł	ourn. Illinois. A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declar the declaratior	ation of the encompass	substances ses all lowe	within the er level mat	manufacture terials for wh	er listed ite	m. Note: nufacture	if the item is an as r has engineering	sembly with low responsibility.	
	1.1 IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials a					als and Mfg	and Mfg Information			
Supplier Information															
Company name* Co			Company unique ID			Unique ID Authority					Response Date*				
ısemi											2023-06-08				
Contact Name	tet Name Title - Contact				Phone - Contact*						Email - Contact*				
Product-Env-Stewards Product Envi			riro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Repres			sentative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item	Number Mfr Item Name				Effective Da	Effective Date Version Manufacturing Si		ring Site	W	eight*	UOM	Unit Type		
	NCP160	NCP160AFCS500T2G CSP LDO 250m		A, Active Discharge		2023-06-08			CNQ		0.	3449	mg	Each	
Ianufacturing Proccess Informat	ion										į		·		
Terminal Plating / Grid Array Ma	Terminal Plating / Grid Array Material Terminal Base Al		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperatur		ure Max Time at Peak Tempe		Temperatu	e Num	ber of Reflow Cyc	eles		
SnAgCu CU Alloy		-	1		260		С	30		seconds	3				
omments															
vel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds												
r more information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select select a RoHS exemption, if applie sigma range of distribution unless	cable [E] enter the weigh	, Requester or Supplier) [B It of the substance or the P	] select the substance of the substance	ance category (JIG or Requester) or [F] Optionally enter the positive (-	enter a value (Supplier). [C] selec -) and negative (-) tolerance in perc	t the substance (JI cent (Note: percer	(G) or enter the substa at tolerance values are	nce and CAS (Other). [D] expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2386	mg	Supplier	Silicon (Si)	7440-21-3		0.2386	mg
Protection coat	0.0085	mg		Polyimide	proprietary data		0.0085	mg
RDL	0.0076	mg	Supplier	Titanium (Ti)	7440-32-6		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0075	mg
Solder Ball	0.0902	mg	Supplier	Silver (Ag)	7440-22-4		0.0023	mg
			Supplier	Tin (Sn)	7440-31-5		0.0873	mg
			Supplier	Copper (Cu)	7440-50-8		0.0005	mg